PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Jia-Rui HU	06/02/2011
Te-Chih HUANG	06/02/2011
Chih-Ming KE	06/02/2011
Hua-Tai LIN	06/02/2011
Tsai-Sheng GAU	06/02/2011

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13152135

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 2010-1039 / 24061.1759

PATENT

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NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=1759_Assignment#page1.tif source=1759_Assignment#page2.tif source=1759_Assignment#page3.tif	

PATENT REEL: 026767 FRAME: 0423

1039

Docket No.: 2010-1309/24061.1759

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1)	Jia-Rui Hu	of	11F-2, No. 96-30, Gongyequ 1st Road, Xitun District Taichung City 407, Taiwan, R.O.C.
(2)	Te-Chih Huang	of	No. 35, Lane 53, Alley 268, Shin-Ming Street Chu-Bei City, Shin-Chu County, Taiwan, R.O.C.
(3)	Chih-Ming Ke	of	9F, No. 17, Alley 7, Lane 298, Sec. 2, Guangfu Road Hsinchu City 300, Taiwan, R.O.C.
(4)	Hua-Tai Lin	of	3F, No. 2-6, Bamboo Road 7th Hsinchu Science Park Hsinchu 300, Taiwan, R.O.C.
(5)	Tsai-Sheng Gau	of	No. 35, Lane 4, An-Kang Street Hsinchu City, Taiwan, R.O.C.

have invented certain improvements in

EXTRACTION OF SYSTEMATIC DEFECTS

for which we have executed an application for Letters Patent of the United States of America,

	of even date filed herewith; and		
XX	filed on June 2, 2011 and assigned application no.	· <u>13/152,135</u>	and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Jia-Rui Hu

Residence Address:

11F-2, No. 96-30, Gongyequ 1st Road, Xitun District

Taichung City 407, Taiwan, R.O.C.

Dated: June 02, 2011

Inventor Signature

Inventor Name:

Te-Chih Huang

Residence Address:

No. 35, Lane 53, Alley 268, Shin-Ming Street

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Dated: June 02, 2011

Te-Ch h Hrang
Inventor Signature

Inventor Name:

Chih-Ming Ke

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Dated: June 02, 2011

Inventor Signature

Docket No.: 2010-1309 / 24061.1759

Customer No.: 42717

Inventor Name:

Hua-Tai Lin

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Dated: 06/02/7011

Inventor Signature

Inventor Name:

Tsai-Sheng Gau

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Dated: 2011, 6,2.

Inventor Signature

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RECORDED: 08/17/2011

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